

SMAG Plastic-Encapsulate Diodes

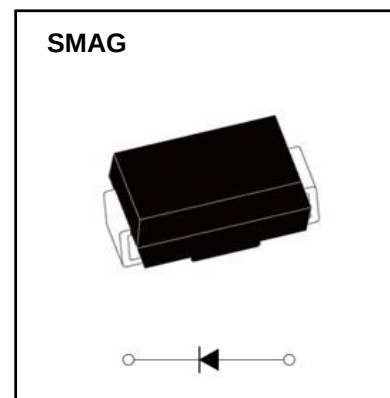
Super Fast Recovery Rectifier Diode

Features

- I_O 2A
- V_{RRM} 50V-600V
- Low forward voltage drop
- High surge current capability
- Glass passivated chip junction

Mechical Data

- Molding compound: UL flammability classification rating 94V-0
- Terminals: Solder plated, solderable per MIL- STD-202, Method 208
- Polarity: Color band denotes cathode end



Limiting Values(Absolute Maximum Rating)

Item	Symbol	Unit	Test Conditions	ES2							
				A	B	C	D	E	G	H	J
Repetitive Peak Reverse Voltage	V _{RRM}	V		50	100	150	200	300	400	500	600
MaximumRMS Voltage	V _{RMS}	V		35	70	105	140	210	280	350	420
Average Forward Current	I _{F(AV)}	A	60Hz Half-sine wave, Resistance load	2.0							
Surge(Non-repetitive)Forward Current	I _{FSM}	A	60Hz Half-sine wave, 1 cycle, Ta=25℃	50							
Operation Junction and Storage Temperature Range	T _J ,T _{STG}	℃		-55 ~ +150							

Electrical Characteristics ($T=25^\circ\text{C}$ Unless otherwise specified)

Item	Symbol	Unit	Test Condition		ES2						
					A	B	C	D	E	G	H
Peak Forward Voltage	V _F	V	I _F =2.0A		0.95			1.25		1.7	
Maximum reverse recovery time	t _{rr}	ns	I _F =0.5A,I _R =1.0A,I _{rr} =0.25A		35						
Peak Reverse Current	I _{RRM1}	μA	V _{RM} =V _{RRM}	T _a =25℃	5.0						
	T _a =125℃			50							
Thermal Resistance(Typical)	R _{θJ-A}	℃/W	Between junction and ambient		75						
	R _{θJ-L}		Between junction and terminal		27						
Juction Capacitance (Typical)	C _j	pF	Measured at 1MHZ and Applied Reverse Voltage of 4.0 V.D.C		26			20			

Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on FR4 PCB double sided copper mini pad

Typical Characteristics

FIG.1: FORWARD CURRENT DERATING CURVE

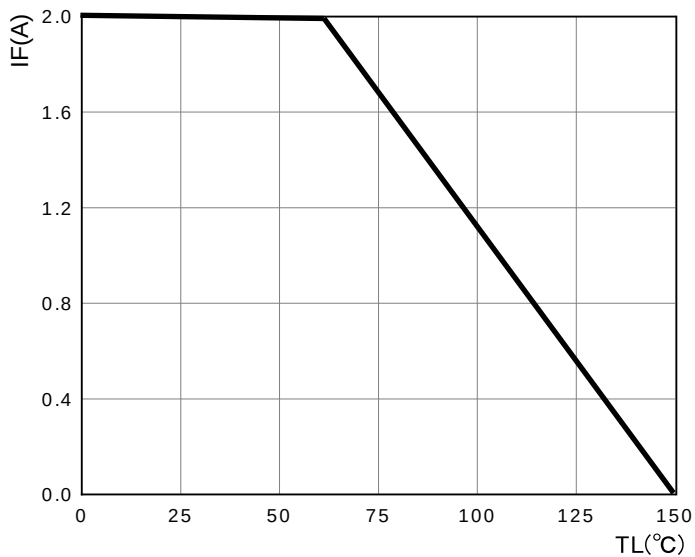
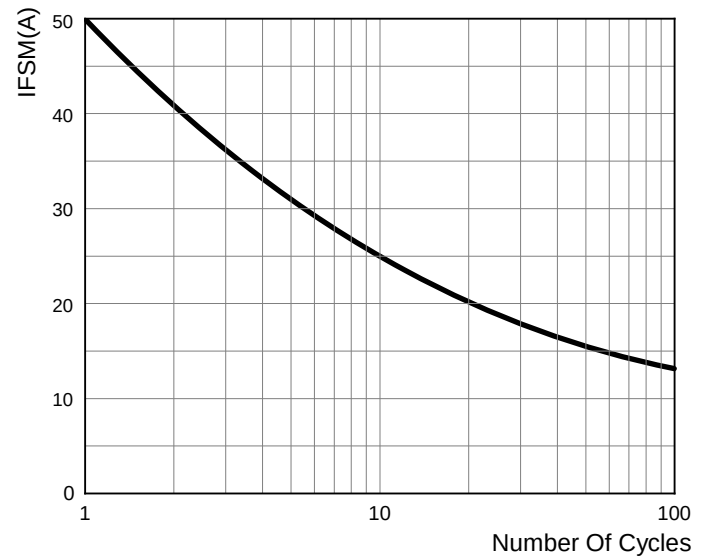
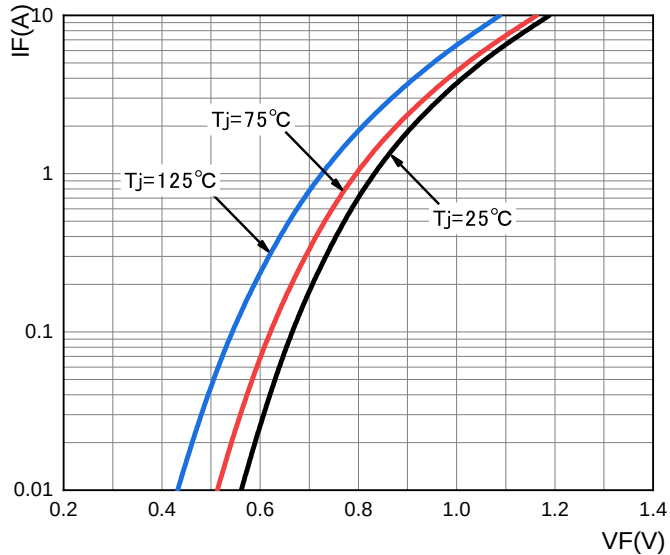


FIG 2: MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT



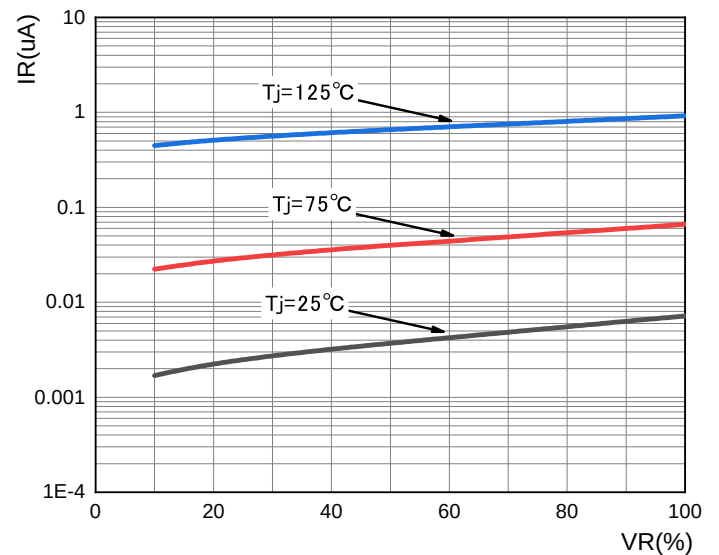
ES2A-ES2D

FIG.3 : TYPICAL FORWARD CHARACTERISTICS



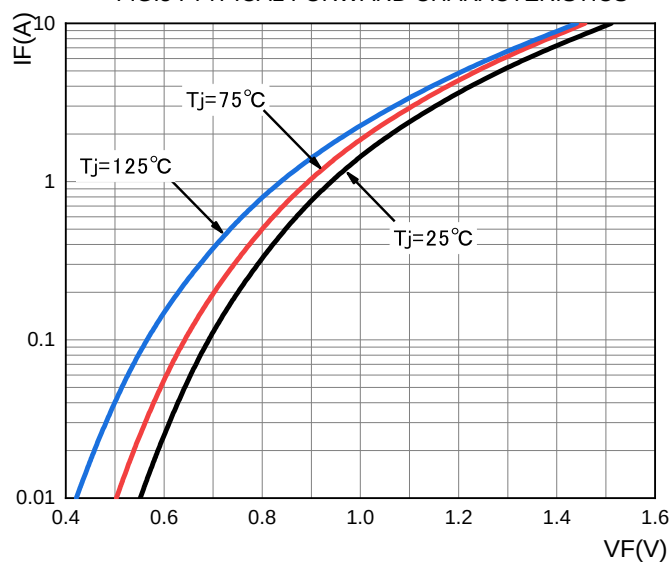
ES2A-ES2D

FIG.4 TYPICAL REVERSE CHARACTERISTICS



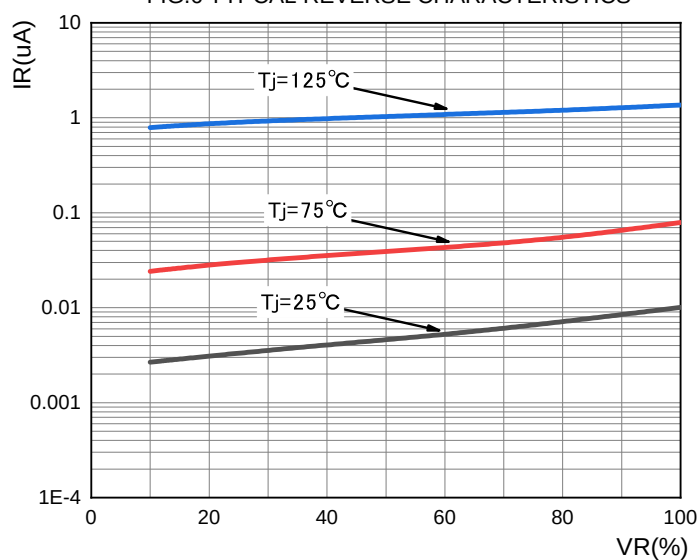
ES2E-ES2G

FIG.5 : TYPICAL FORWARD CHARACTERISTICS



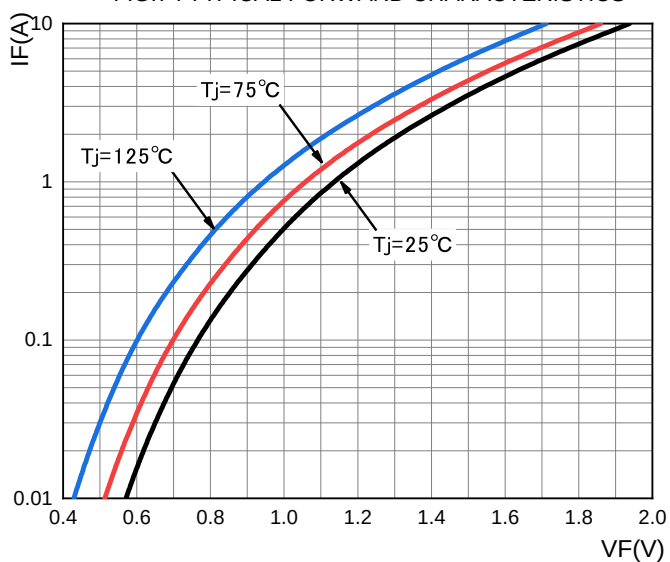
ES2E-ES2G

FIG.6 TYPICAL REVERSE CHARACTERISTICS



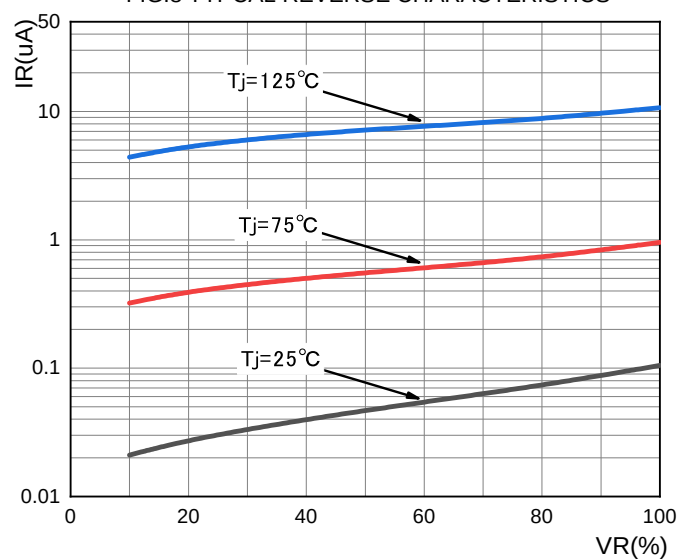
ES2H-ES2J

FIG.7 : TYPICAL FORWARD CHARACTERISTICS

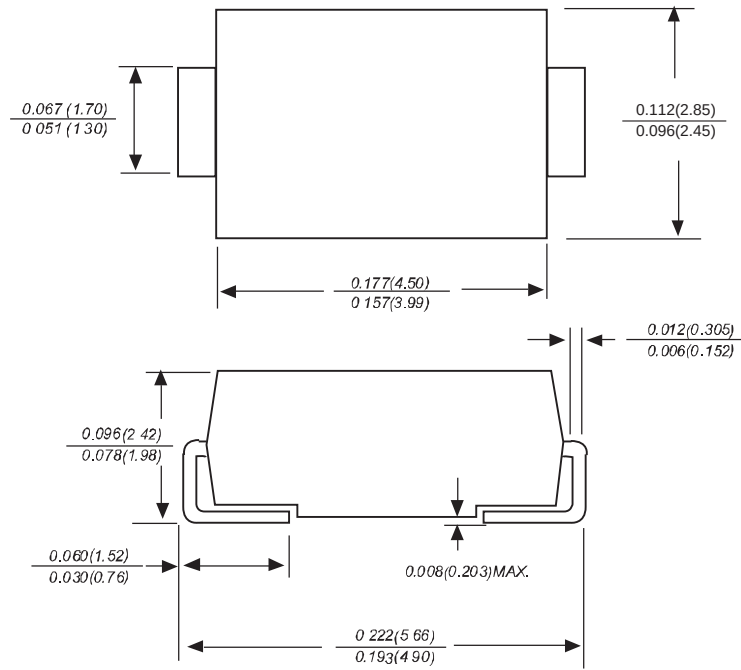


ES2H-ES2J

FIG.8 TYPICAL REVERSE CHARACTERISTICS

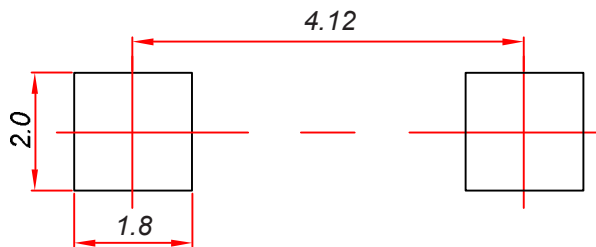


SMAG Package Outline Dimensions



Dimensions in inches and (millimeters)

SMAG Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.

Ordering Information

Part Number	Package	Shipping Quantity
ES2A-ES12J	SMAG	5000/tape&Reel

Marking Diagram



X: From A To J

Reel Taping Specifications For Surface Mount Devices- SMAG

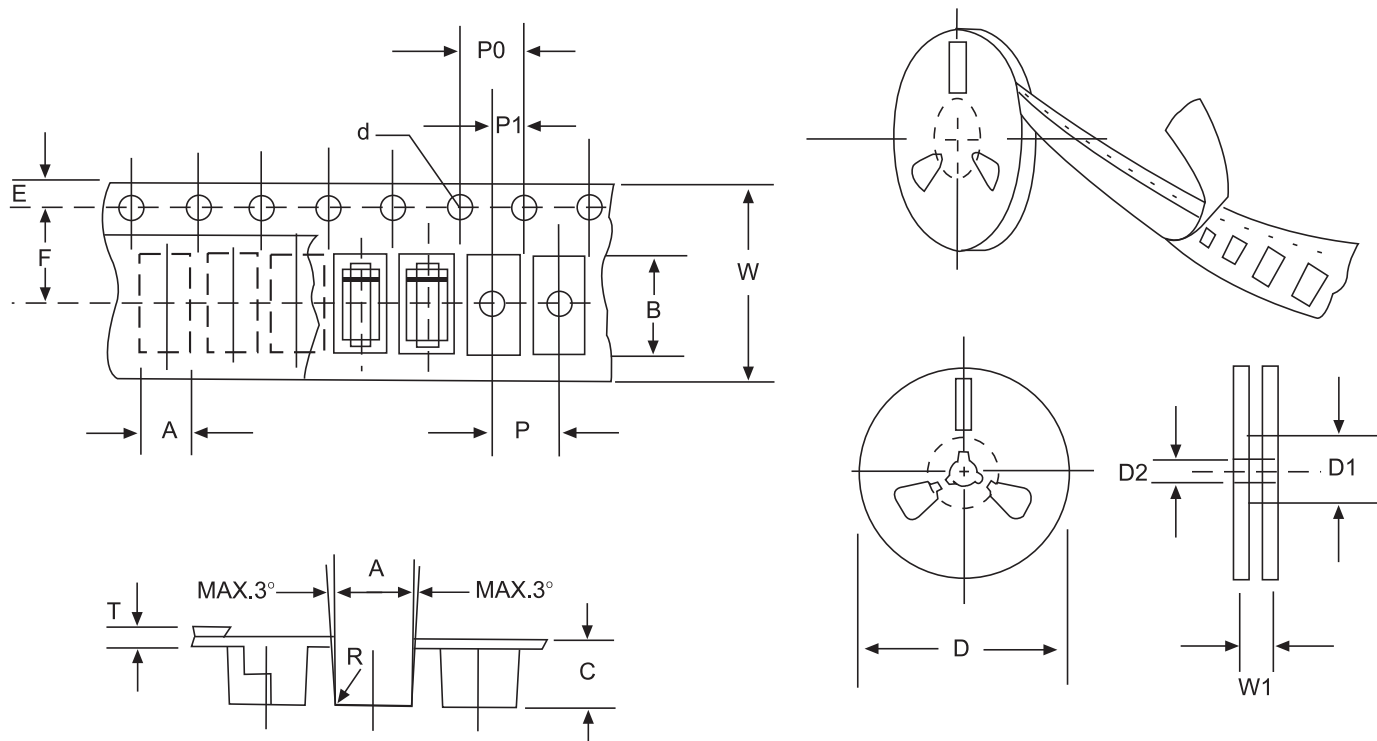


Fig:CONFIGURATION OF FLAT MELF TAPING

ITEM	SYMBOL	SMAG mm(inch)
Carrier width	A	2.79±0.1(0.110±0.004)
Carrier length	B	5.33±0.1(0.210±0.004)
Carrier depth	C	2.36±0.1(0.093±0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	279±2.0 (11± 0.079)
Reel inner diameter	D1	75 ±1.0 (2.95 ±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Sprocket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	5.5±0.05(0.217±0.002)
Punch hole pitch	P	4.0±0.1(0.157±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Total tape thickness	T	0.28±0.02(0.011 ±0.0008)
Tape width	W	12.0±0.2(0.472±0.008)
Reel width	W1	16.8±2.0(0.661±0.079)

NOTE: Devices are packed in accordance with EIA standard RS-481-A and specification given above.